

# Claims

[c1]

Claim 1:

A modular electronic device where non-direct electrical contact (non-contact) mechanisms are used for inter-module communication, and where modules are attached forming an extendable structure with extendable function.

[c2]

Claim 2:

A modular device as in Claim 1 where non-direct electrical contact control mechanisms are used.

[c3]

Claim 3:

A modular device as in Claim 1 where inter-module power is distributed using magnetic induction/transformer action.

[c4]

Claim 4:

A modular device as in Claim 1 where modules are liquid filled for cooling.

[c5]

Claim 5:

A modular device as in Claim 1 where modules are liquid filled for withstanding a high-pressure environment.

[c6]

Claim 6:

A modular device as in Claim 1 where inter-module power is distributed using a non-contact power distribution mechanism.

[c7]

Claim 7:

A modular device as in Claim 1 where the modules are sealed.

[c8]

Claim 8:

A modular device as in Claim 1 where devices are internally powered.

[c9]

Claim 9:

A modular device as in Claim 1 where power is distributed through direct electric power interconnects.

[c10]

Claim 10:

A modular device as in Claim 1 where alignment mechanisms and retention mechanisms are used to align and attach modules.

Regarding: A robust modular electronic device without direct electrical connections for inter-module communication or control. By Robert J. Rapp, Customer Number 41400

[c11]

Claim 11:

A modular device as in Claim 1 where alignment mechanisms are used as a transformer core.

[c12]

Claim 12:

A modular device as in Claim 1 where alignment mechanisms are used to improve the efficiency of non-contact power distribution mechanisms.

[c13]

Claim 13:

A system comprised of a plurality of devices described in Claim 1 and preceding Claims as they comprise a failure resistant extendable methodology for building robust electronic systems.